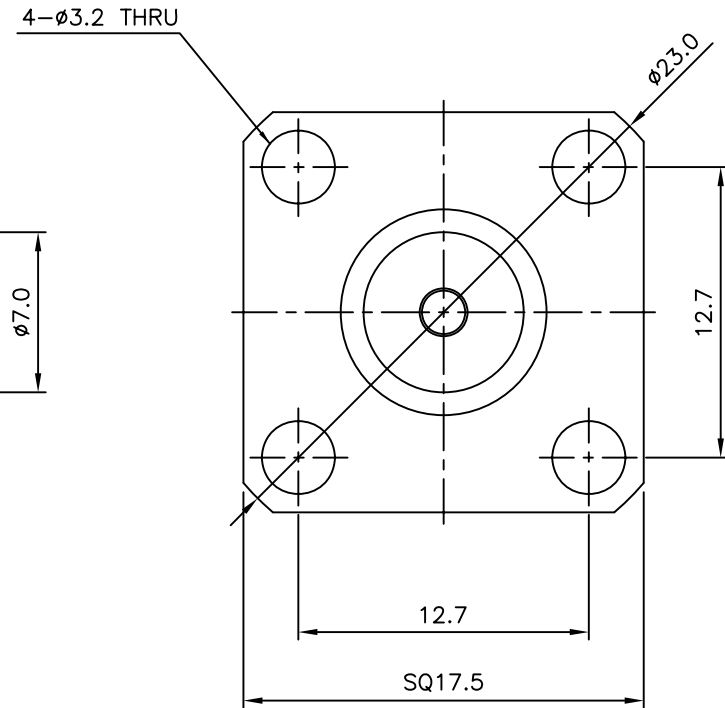
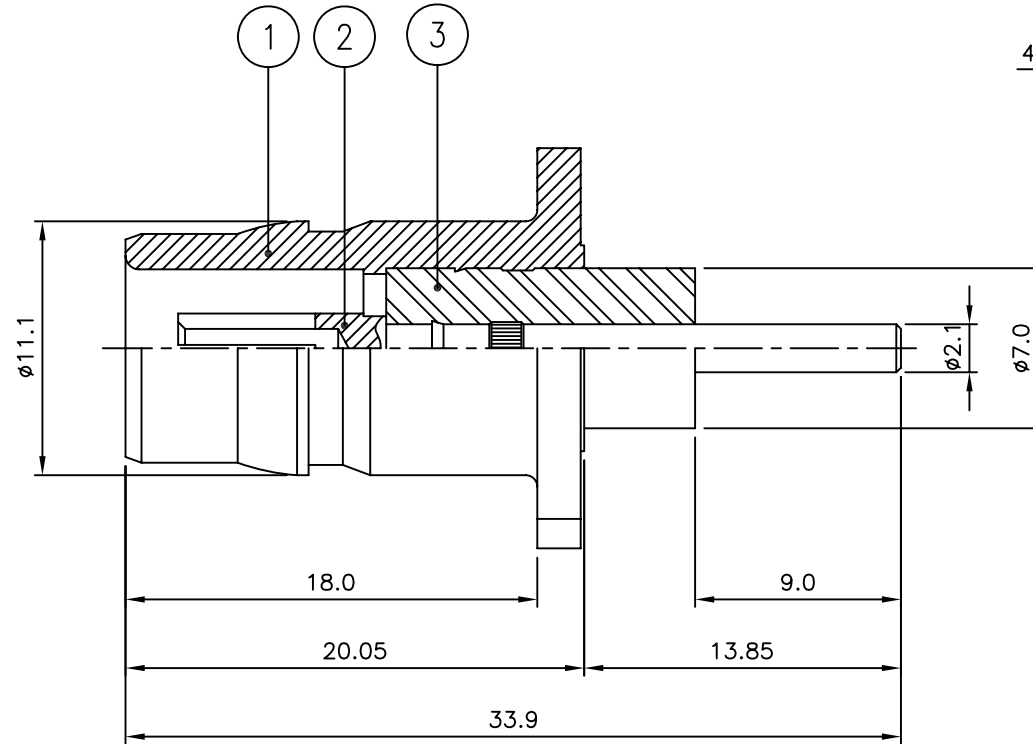


REVISION				
REV	DESCRIPTION	DRAWN	APPR	DATE
IR	Initial Registration	H.J.LEE	I.C.KIM	2016.02.01.



* 조립방법

1. BODY에 TEFLON을 조립한다.
2. 조립된 TEFLON에 PIN 높이 지그로 PIN을 조립한다.

3	INSULATOR	1	TEFLON		DIN02720-N/1
2	CONTACT	1	BeCu C17300	Silver 3.0 μ m	DCT03640-5/1
1	BODY(A)	1	MBsBD C3604BD-F	SUCO 3.0 μ m	DBD04119-5/1
NO.	DESCRIPTION	Q'TY	MATERIAL	PLATING	CODE

TOLERANCE	Decimal	DATE 2016. 02. 01.		 RF & MICROWAVE TECHNOLOGY Tel : 82-32-347-8015 Fax : 82-32-347-8017
	Angle	APPROVED BY	I.C.KIM	
MATERIAL		CHECKED BY		KJ COMTECH CO.,LTD. TITLE KQN50 SOLDER END JS-4H
		DRAWN BY	H.J.LEE	
FINISH		SCALE	3/1	A4 DWG NO. CN03555-7/1 REVISION I R SHEET 1 of 1
		UNIT	mm	